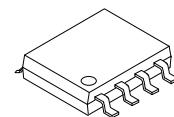
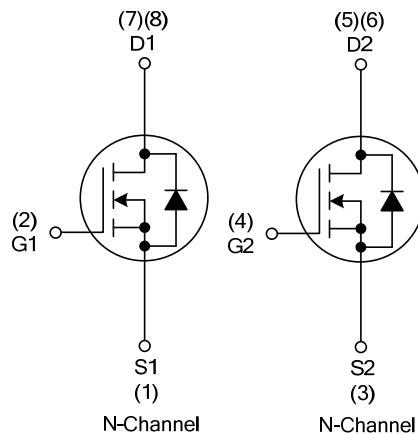


12NN10**Power MOSFET****2.5A, 100V DUAL N-CHANNEL
ENHANCEMENT MODE POWER
MOSFET****■ DESCRIPTION**

The UTC 12NN10 is a dual N-Channel enhancement mode power MOSFET, it provides designer with fast switching speed, ruggedized device design, low on-resistance and cost-effectiveness.

■ FEATURES

- * Low Gate Charge (Typically 14.2nC)
- * $R_{DS(ON)} < 0.18\Omega$ @ $V_{GS}=10V$, $I_D=2.0A$
- * Fast Switching Speed
- * Simple Drive Requirement

■ SYMBOL

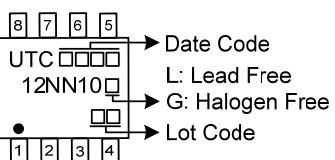
SOP-8

■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment							Packing
Lead Free	Halogen Free		1	2	3	4	5, 6	7, 8		
12NN10G-S08-R	12NN10G-S08-R	SOP-8	S1	G1	S2	G2	D2	D1	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source

12NN10G-S08-R	(1)Packing Type (2)Package Type (3)Green Package	(1) R: Tape Reel (2) S08: SOP-8 (3) G: Halogen Free and Lead Free, L: Lead Free
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■ MARKING

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	Continuous(Note 3)	I_D	2.5	A
	Pulsed(Note 2)	I_{DM}	10	A
Power Dissipation		P_D	2	W
Junction Temperature		T_J	-40 ~ +150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Pulse width limited by Max. junction temperature.

3. Surface mounted on 1 in² copper pad of FR4 board, t <10sec ; 135°C/W when mounted on Min. copper pad.

■ THERMAL DATA

PARAMETER	SYMBOL	RATING	UNIT
Junction to Ambient	θ_{JA}	62.5	$^\circ\text{C}/\text{W}$

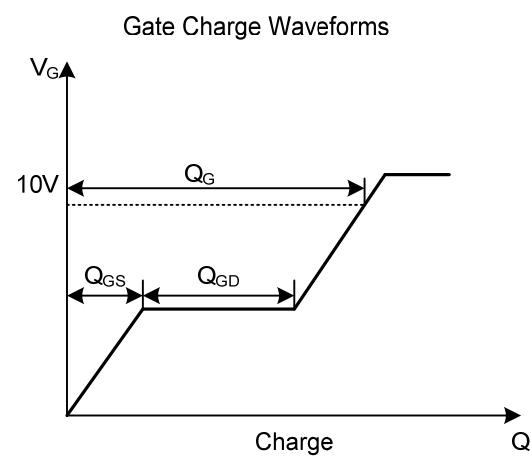
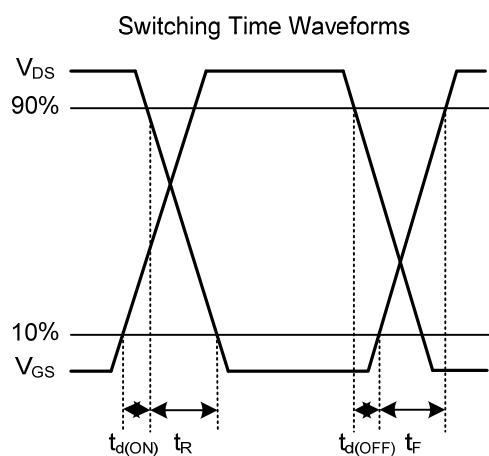
Note: Surface mounted on 1 in² copper pad of FR4 board, t <10sec ; 135°C/W when mounted on Min. copper pad.

■ ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$, unless otherwise specified)

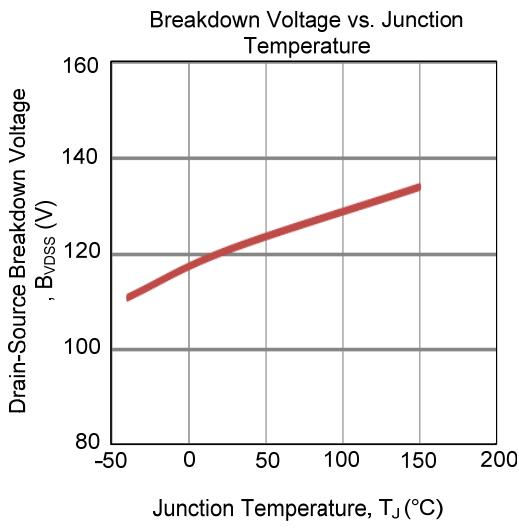
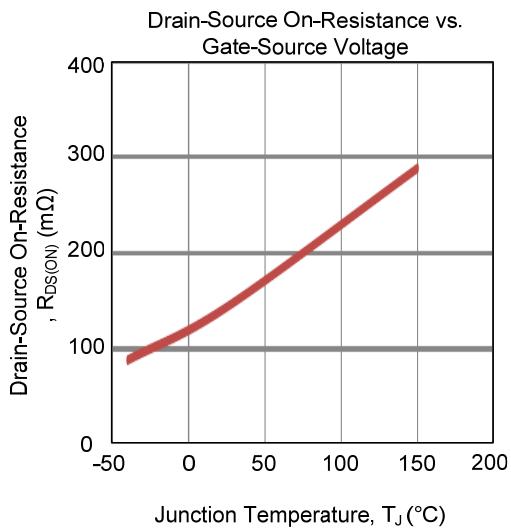
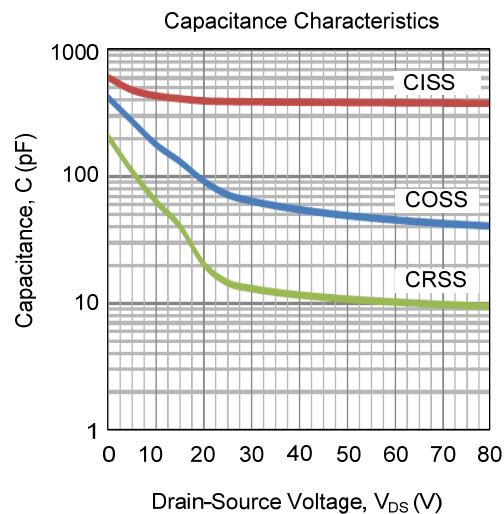
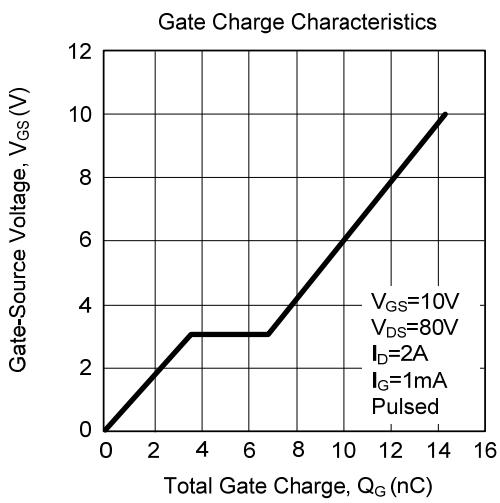
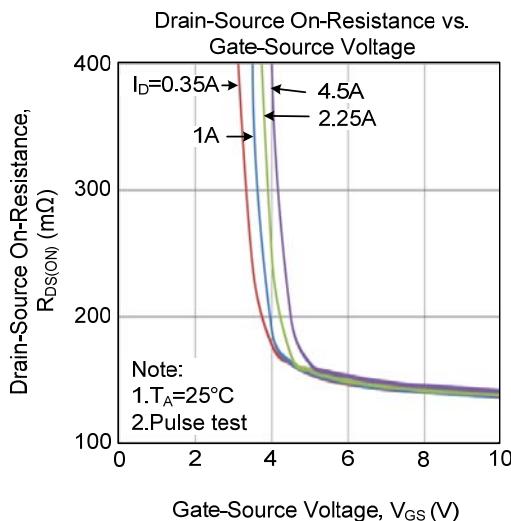
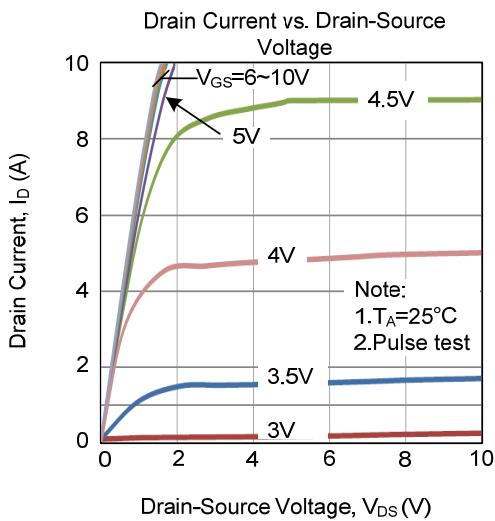
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=80\text{V}, V_{GS}=0\text{V}$			10	μA
Gate-Source Leakage Current	Forward	$V_{DS}=0\text{V}, V_{GS}=20\text{V}$			100	nA
	Reverse	$V_{DS}=0\text{V}, V_{GS}=-20\text{V}$			-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		3.0	V
Drain-Source On-State Resistance (Note 1)	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=2.0\text{A}$		0.15	0.18	Ω
Forward Transconductance	g_{FS}	$V_{DS}=10\text{V}, I_D=2.0\text{A}$		2.8		S
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$		390		pF
Output Capacitance	C_{OSS}			71		pF
Reverse Transfer Capacitance	C_{RSS}			14		pF
SWITCHING PARAMETERS						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=80\text{V}, V_{GS}=5\text{V}, I_D=2.0\text{A}$ $I_G=1\text{mA}$		8.8		nC
Total Gate Charge (Note 1)	Q_G	$V_{DS}=80\text{V}, V_{GS}=10\text{V},$ $I_D=2.0\text{A}, I_G=1\text{mA}$		14.2		nC
Gate-Source Charge	Q_{GS}			3.6		nC
Gate-Drain Charge	Q_{GD}			3.2		nC
Turn-ON Delay Time (Note 1)	$t_{D(\text{ON})}$	$V_{DS}=50\text{V}, I_D=2\text{A}, R_G=3.3\Omega$ $V_{GS}=10\text{V}$		6.5		ns
Turn-ON Rise Time	t_R			7		ns
Turn-OFF Delay Time	$t_{D(\text{OFF})}$			14		ns
Turn-OFF Fall Time	t_F			3.5		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_S=1.5\text{A}, V_{GS}=0\text{V}$			1.3	V
Body Diode Reverse Recovery Time (Note 1)	t_{rr}	$V_{GS}=0\text{V}, I_S=2.0\text{A},$ $dI_F/dt=100\text{A}/\mu\text{s}$		40		ns
Body Diode Reverse Recovery Charge	Q_{rr}			75		nC

Note: Pulse test.

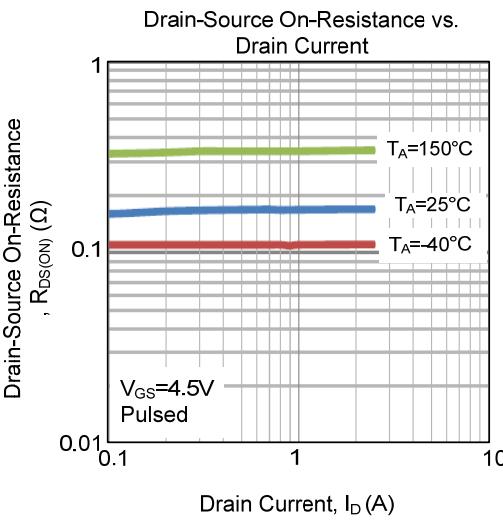
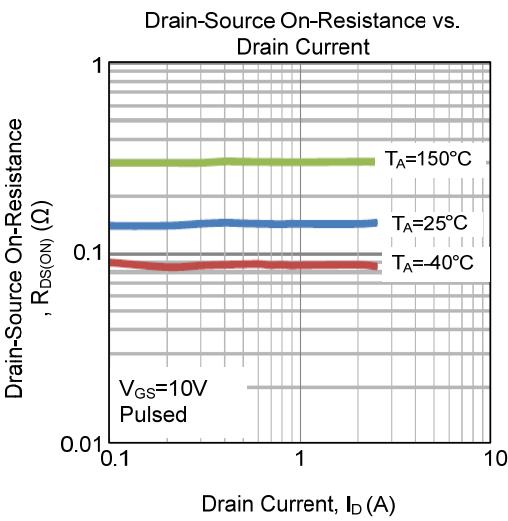
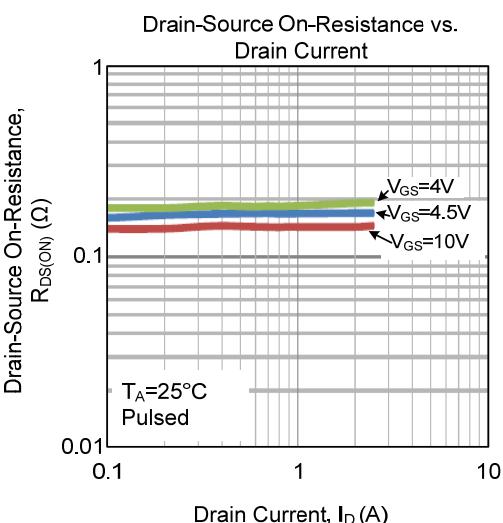
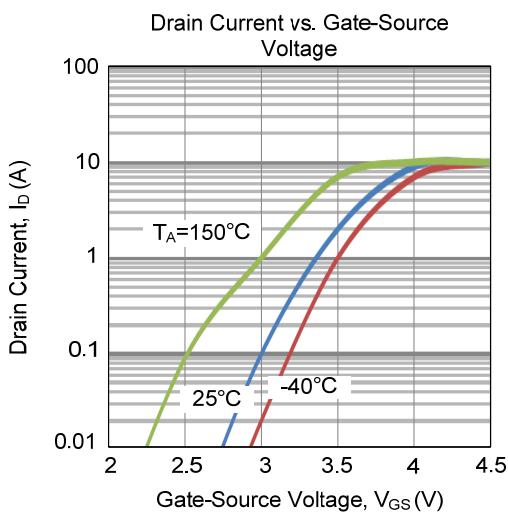
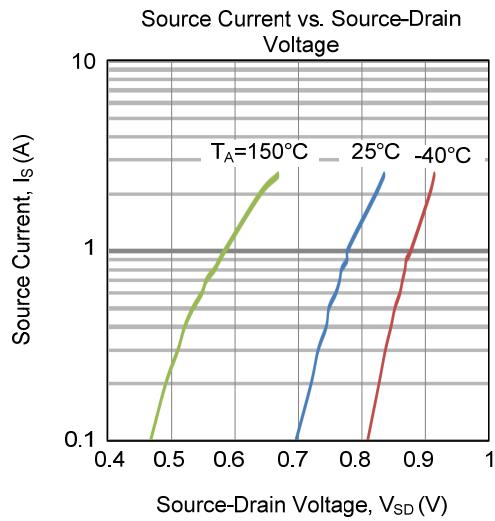
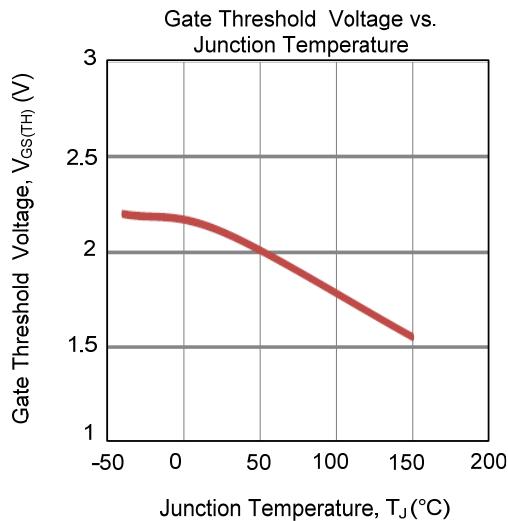
- TEST CIRCUITS AND WAVEFORMS



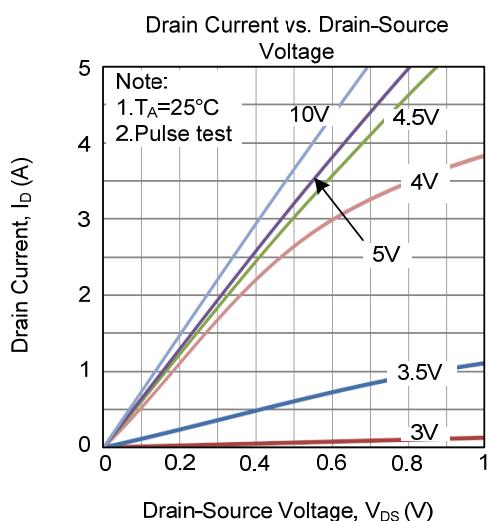
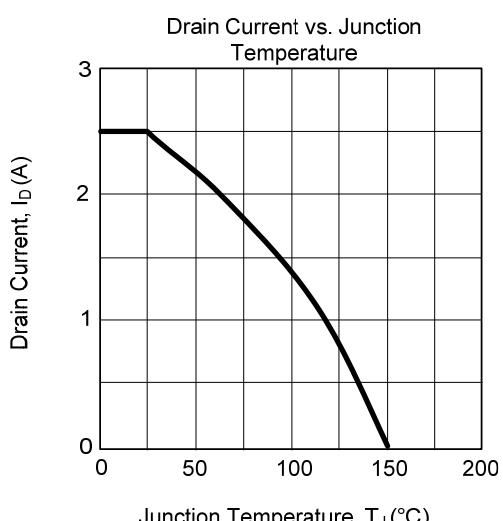
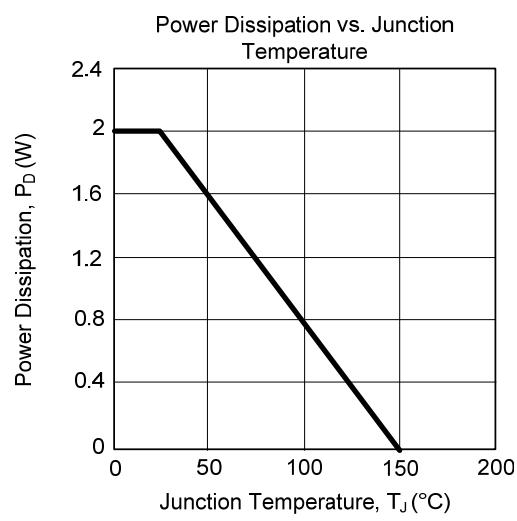
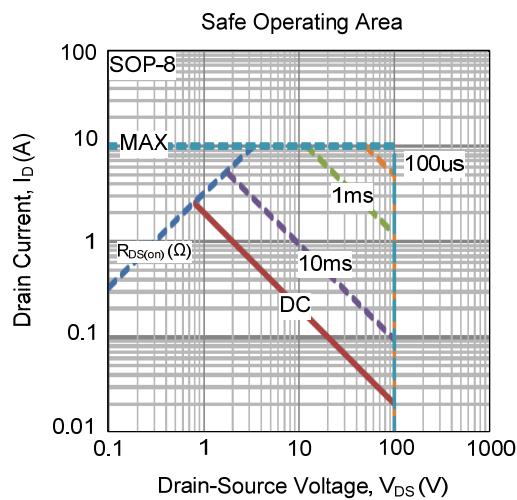
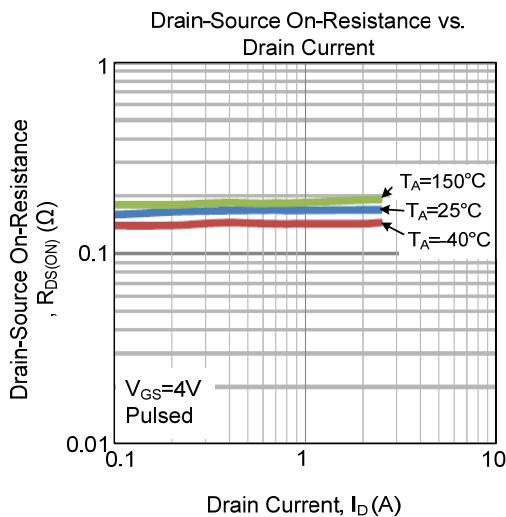
■ TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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